2025 IEEE 75th Electronic Components and Technology Conference

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For Immediate Release

# *2025 IEEE Electronic Components and Technology Conference Announces Student Competition; Proposals Must be Submitted by November 30, 2024*

DALLAS, TX (November 5, 2024) – The IEEE Electronic Components and Technology Conference (ECTC), the premier technical conference and product exhibition for the world's semiconductor packaging industry, has announced a Student Competition for ECTC 2025, the conference's 75th anniversary. Three winning student teams will receive the opportunity to attend ECTC 2025 for free, including travel costs up to a specified amount.

More than 2,000 scientists, engineers and businesspeople from more than 20 countries are expected to attend the 75th annual ECTC, which will take place May 27-30, 2025 at the Gaylord Texan Resort & Convention Center in Dallas.

"This is a great chance for students to showcase their skills and present their innovative ideas to industry movers and shakers, in competition with other student teams from around the world," said Przemyslaw Gromala, ECTC 2025 Program Chair and Sr. Expert & Simulation Team Leader at Robert Bosch GmbH. "At ECTC 2025, the winning teams will be able to learn about state-of-the-art industry advances; network with technical and industry experts and potential employers; and have the opportunity for their work to be published in the highly regarded technical journal, *IEEE Transactions on Components, Packaging and Manufacturing Technology*."

The ECTC organizing committee is inviting teams of up to a maximum of three students. Eligible participants can be undergraduate (BSc), master's (MSc), or doctoral (PhD) candidates from any university, and should be currently enrolled in an academic program. Interested student teams must submit a two-page project outline, including a literature review, their project idea, and expected outcomes, by **November 30, 2024**.

They must select one of the following five pre-defined challenges, each one dealing with a critical aspect of simulation and reliability in electronic packaging. By focusing on these areas,

students will contribute to the development of more reliable, efficient, and cost-effective future electronic and photonic systems:

- Predictive Modeling and Mitigation of Warpage in Optical MEMS Bare Die Integration on PCB or Flex Substrate
- Modeling of CTE Mismatch Effects in Multi-Material Packages
- Approaches to Reduce Thermal Resistance and Improve Reliability of High-Temperature Power Electronics Modules
- Exploration of Thermal-Mechanical Challenges for Heterogeneously Integrated Opto-Electronic Packages
- Condition Monitoring Concept of Electronic Components or Systems

**On January 12, 2025,** the organizing committee will announce 10 teams selected for the second round of the competition. These teams will have eight weeks to complete their projects and submit a report. After review by the organizing committee, the three winning teams will be chosen by **March 31, 2025**, and will have until **May 15, 2025** to finalize their work and submit their presentations.

**For more information about the student competition**
Please visit https://www.ectc.net/authors/studentindex.cfm

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**About ECTC, EPS & IEEE**
The ECTC technical program addresses new developments, trends and applications for a broad range of topics, including components, materials, assembly, reliability, modeling, interconnect design and technology, device and system packaging, heterogeneous integration, wafer level packaging, photonics and optoelectronics, IoT, 5G, quantum computing and systems, 2.5D and 3D integration technology, and other emerging technologies relevant to electronics packaging.

The IEEE's Electronics Packaging Society (EPS) sponsors ECTC. EPS is the leading international forum for scientists and engineers engaged in research, design and development of revolutionary advances in microsystems packaging and manufacturing. It encompasses all aspects of packaging and integration of electrical, electronic, optoelectronic, biological, micromechanical and sensing components.

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